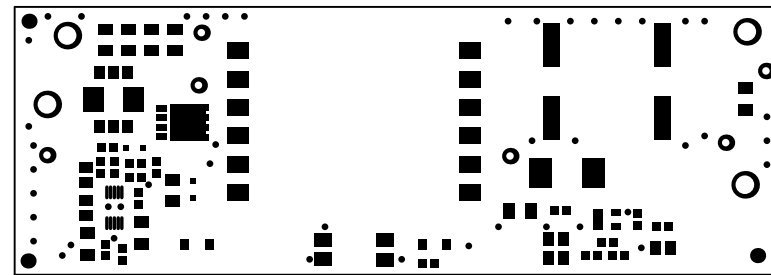
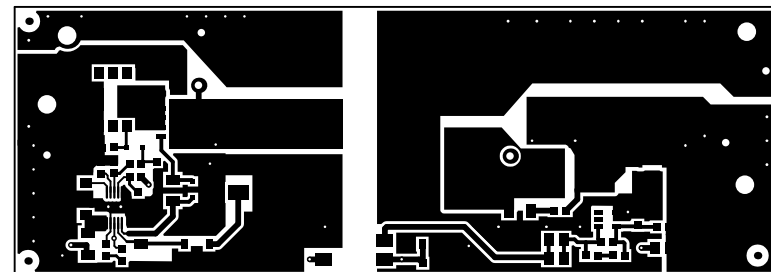


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/19/2012 4:16:01 PM	TEXAS INSTRUMENTS	

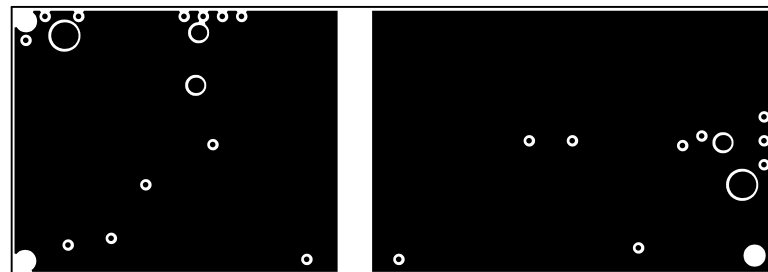


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/19/2012 4:16:01 PM	TEXAS INSTRUMENTS	



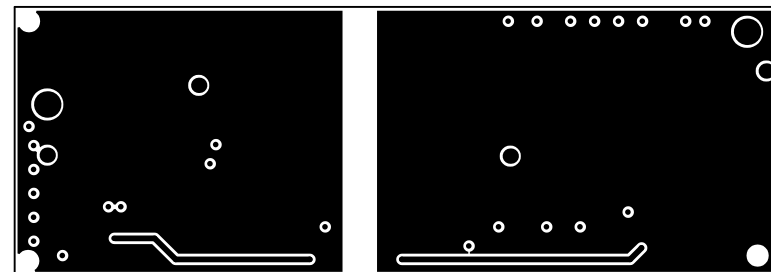
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/19/2012 4:16:02 PM	TEXAS INSTRUMENTS	

DESIGN INFORMATION	
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)	
<u>1400MIL</u>	X <u>4000MIL</u>
Number of Layers :	<u>4</u>
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>7</u> MIL
MIN. VIA PAD SIZE:	<u>22</u> MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL	
MATERIAL:	
<input checked="" type="checkbox"/> FR-4	<input type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
COPPER THICKNESS (FINISHED):	
OUTER:	<input checked="" type="checkbox"/> 1.4MIL (1oz) <input type="checkbox"/> 2MIL (1.4oz) <input type="checkbox"/> 2.8MIL (2oz)
INNER SIGNAL:	<input checked="" type="checkbox"/> 0.7MIL (0.5oz) <input type="checkbox"/> 2.8MIL (2oz)
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	
<input checked="" type="checkbox"/> GREEN	<input type="checkbox"/> BLUE <input type="checkbox"/> OTHER _____
SURFACE FINISH:	
<input type="checkbox"/> IMMERSION GOLD (ENIG)	<input type="checkbox"/> Pb-FREE HASL
<input checked="" type="checkbox"/> OTHER _____	HASL
ARRAY/PANEL:	
<input checked="" type="checkbox"/> CUT AND TRIM PER MECH LAYER 1	<input type="checkbox"/> N.C. ROUTE <input type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3
<input checked="" type="checkbox"/> UL 94V-0	<input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER
MANUFACTURER'S ID/LOGO:	<input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK

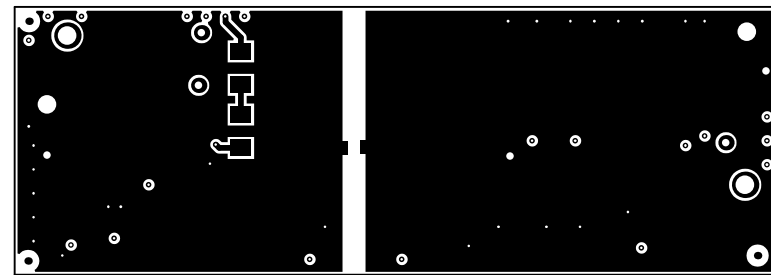


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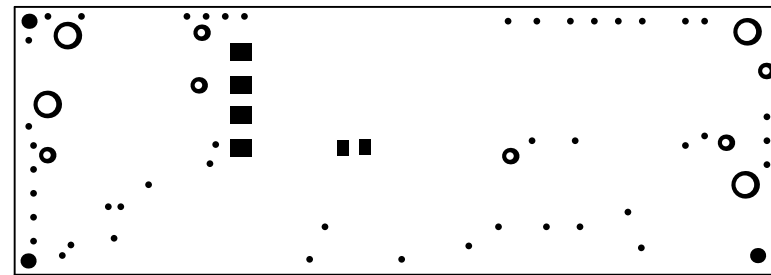
DESIGN INFORMATION	
BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)	
<u>1400MIL</u>	X <u>4000MIL</u>
Number of Layers :	<u>4</u>
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>7</u> MIL
MIN. VIA PAD SIZE:	<u>22</u> MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- <u>5</u> MIL, HOLES +/- <u>3</u> MIL	
MATERIAL:	
<input checked="" type="checkbox"/> FR-4	<input type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____
THICKNESS:	<input checked="" type="checkbox"/> 62 MIL (1.6mm) +/-10% <input type="checkbox"/> OTHER _____
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
COPPER THICKNESS (FINISHED):	
OUTER:	<input checked="" type="checkbox"/> 1.4MIL (1oz) <input type="checkbox"/> 2MIL (1.4oz) <input type="checkbox"/> 2.8MIL (2oz)
INNER SIGNAL:	<input checked="" type="checkbox"/> 0.7MIL (0.5oz) <input type="checkbox"/> 2.8MIL (2oz)
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	
<input checked="" type="checkbox"/> GREEN	<input type="checkbox"/> BLUE <input type="checkbox"/> OTHER _____
SURFACE FINISH:	
<input type="checkbox"/> IMMERSION GOLD (ENIG)	<input type="checkbox"/> Pb-FREE HASL
<input checked="" type="checkbox"/> OTHER _____	HASL
ARRAY/PANEL:	
<input checked="" type="checkbox"/> CUT AND TRIM PER MECH LAYER 1	<input type="checkbox"/> N.C. ROUTE <input type="checkbox"/> V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS ->	<input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3
<input checked="" type="checkbox"/> UL 94V-0	<input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER
ADDITIONAL REQUIREMENTS:	
MICROSECTION:	<input type="checkbox"/> YES
BARE BOARD ELEC. TEST:	<input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER
MANUFACTURER'S ID/LOGO:	<input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK



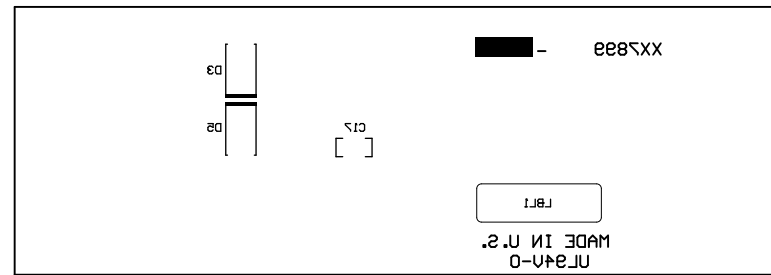
M10B5abdN0t65i ne



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/19/2012 4:16:03 PM	TEXAS INSTRUMENTS	

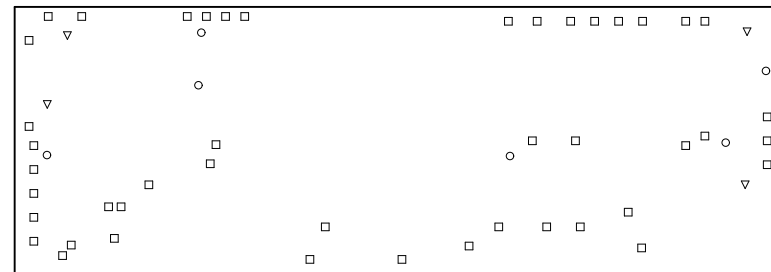


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/19/2012 4:16:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/19/2012 4:16:04 PM	TEXAS INSTRUMENTS	

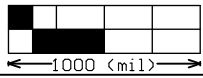
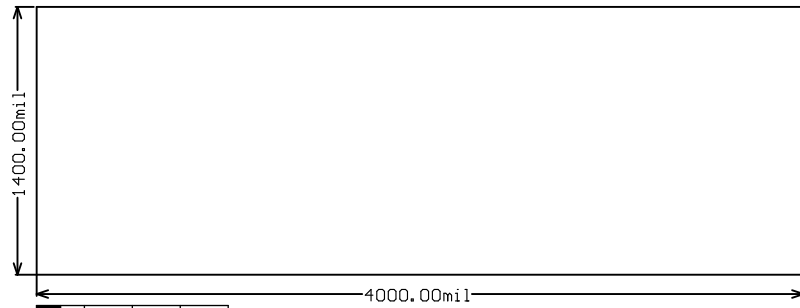




Symbol	Hit Count	Tool Size	Plated	Hole Type
□	45	15mil (0.381mm)	PTH	Round
○	6	40mil (1.016mm)	PTH	Round
▽	4	98.425mil (2.5mm)	PTH	Round
	55 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/19/2012 4:16:04 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7899	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/19/2012 4:16:04 PM	TEXAS INSTRUMENTS	

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